

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings of claims in the application:

**Listing of Claims:**

Claims 1.-8. (canceled)

Claim 9. (original) A method of making a chip device, the method comprising:

providing a die;

providing a leadframe including a die attach cavity and a plurality of dimples defined around a periphery of the leadframe, the die attach cavity having substantially the same thickness as the die;

placing solder balls into the dimples; and

flipping the die into the die attach cavity and attaching it therein.

Claim 10. (original) The method of claim 9 wherein the die provided is a bumped die.

Claim 11(new) The method of claim 9 wherein the die comprises a MOSFET.

Claim 12. (new) The method of claim 9 further comprising placing solder on the die.

Claim 13. (new) The method of claim 9 wherein the leadframe comprises a copper based alloy.

Claim 14. (new) The chip device of claim 9 wherein the leadframe includes a solderable coating.

Claim 15. (new) The method of claim 9 wherein the die comprises source and gate connections.

Claim 16. (new) The method of claim 9 wherein the leadframe comprises a Ni-Pd coating.